

# FDD6780A / FDU6780A\_F071

## N-Channel PowerTrench® MOSFET

25 V, 8.6 mΩ

### Features

- Max  $r_{DS(on)}$  = 8.6 mΩ at  $V_{GS} = 10$  V,  $I_D = 16.4$  A
- Max  $r_{DS(on)}$  = 19.0 mΩ at  $V_{GS} = 4.5$  V,  $I_D = 12.2$  A
- 100% UIL test
- RoHS Compliant

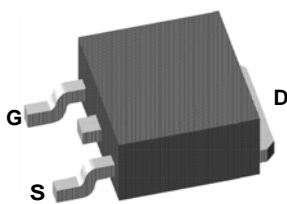


### General Description

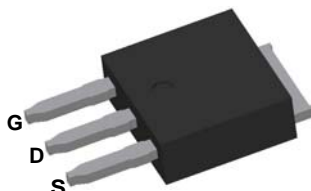
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{DS(on)}$  and fast switching speed.

### Applications

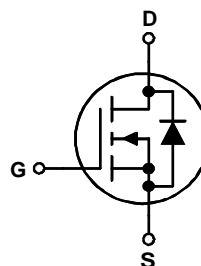
- Vcore DC-DC for Desktop Computers and Servers
- VRM for Intermediate Bus Architecture



**D-PAK  
(TO-252)**



**Short-Lead I-PAK  
(TO-251AA)**



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	25	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	30	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	48	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	16.4	
	-Pulsed	100	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	24	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	32.6	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.7	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case TO-252, TO-251	4.6	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252 (Note 1a)	40	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD6780A	FDD6780A	D-PAK (TO-252)	13 "	12 mm	2500 units
FDU6780A	FDU6780A_F071	TO-251AA	N/A(Tube)	N/A	75 units

**Electrical Characteristics**  $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
--------	-----------	-----------------	-----	-----	-----	-------

**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	25			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		14		mV/ $^{\circ}\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$			$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\text{ }\mu\text{A}$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		-5		mV/ $^{\circ}\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 16.4\text{ A}$		6.8	8.6	m $\Omega$
		$V_{GS} = 10\text{ V}$ , $I_D = 16.4\text{ A}$ Short-Lead I-PAK version		7.0	8.8	
		$V_{GS} = 4.5\text{ V}$ , $I_D = 12.2\text{ A}$		14.1	19.0	
		$V_{GS} = 4.5\text{ V}$ , $I_D = 12.2\text{ A}$ Short-Lead I-PAK version		14.3	19.2	
		$V_{GS} = 10\text{ V}$ , $I_D = 16.4\text{ A}$ , $T_J = 150\text{ }^{\circ}\text{C}$		10.3	13.0	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{ V}$ , $I_D = 16.4\text{ A}$		70		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 13\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$		927	1235	pF
$C_{oss}$	Output Capacitance			197	265	pF
$C_{rss}$	Reverse Transfer Capacitance			181	275	pF
$R_g$	Gate Resistance	$f = 1\text{ MHz}$		1.2		$\Omega$

**Switching Characteristics**

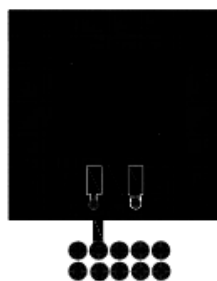
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 13\text{ V}$ , $I_D = 16.4\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		7	14	ns
$t_r$	Rise Time			3	10	ns
$t_{d(off)}$	Turn-Off Delay Time			16	29	ns
$t_f$	Fall Time			3	10	ns
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to $10\text{ V}$	$V_{DD} = 13\text{ V}$ , $I_D = 16.4\text{ A}$	17	24	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to $5\text{ V}$		9.2	13	nC
$Q_{gs}$	Gate to Source Charge			2.8		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			4.0		nC

**Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 3.1\text{ A}$ (Note 2)		0.8	1.2	V
		$V_{GS} = 0\text{ V}$ , $I_S = 16.4\text{ A}$ (Note 2)		0.9	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 16.4\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		15	27	ns
$Q_{rr}$	Reverse Recovery Charge			4	10	nC

Notes:

- 1:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  
 $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.



a) 40 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b) 96 °C/W when mounted on a minimum pad.

- 2: Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%.

- 3:  $E_{AS}$  of 24 mJ is based on starting  $T_J = 25$  °C,  $L = 1$  mH,  $I_{AS} = 7$  A,  $V_{DD} = 23$  V,  $V_{GS} = 10$  V. 100% test at  $L = 0.1$  mH,  $I_{AS} = 13$  A.

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

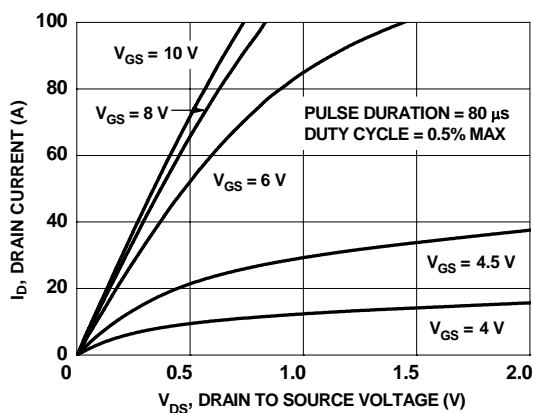


Figure 1. On-Region Characteristics

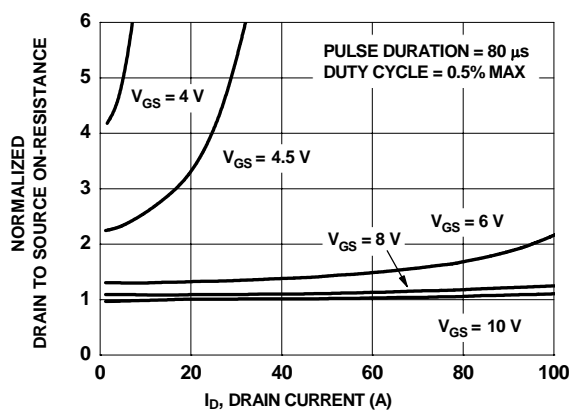


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

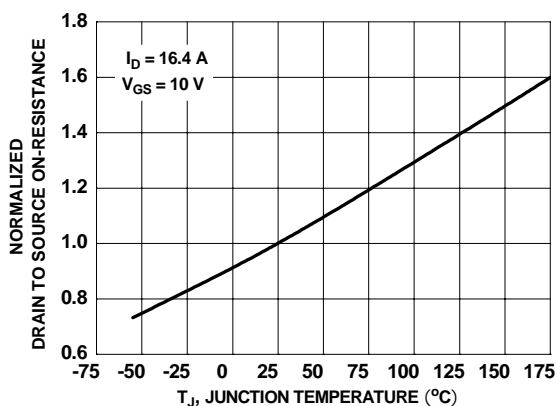


Figure 3. Normalized On-Resistance vs Junction Temperature

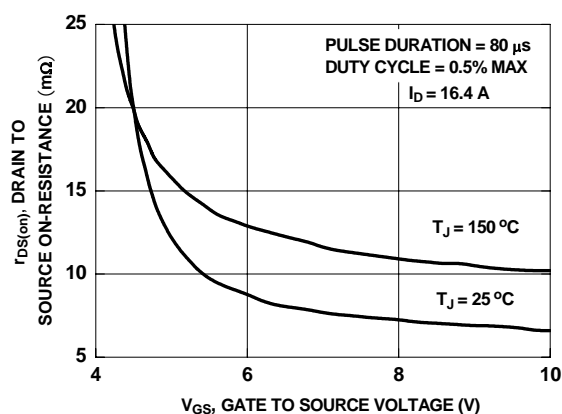


Figure 4. On-Resistance vs Gate to Source Voltage

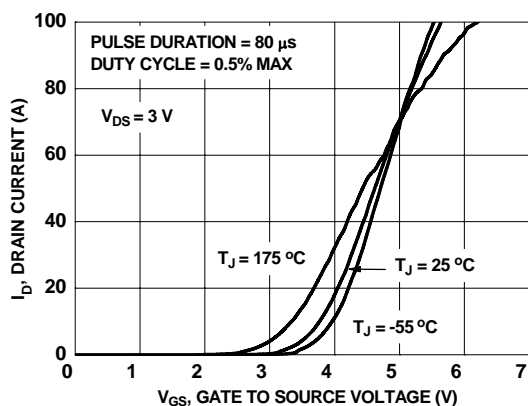


Figure 5. Transfer Characteristics

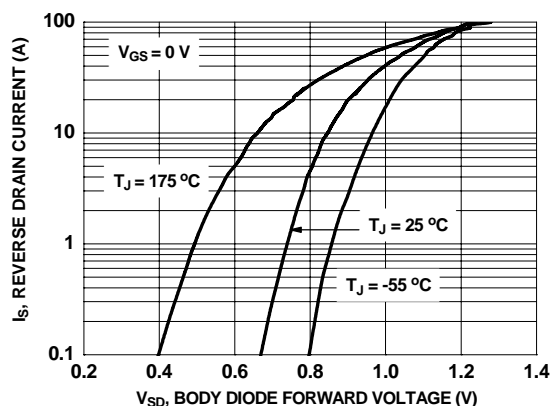


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted

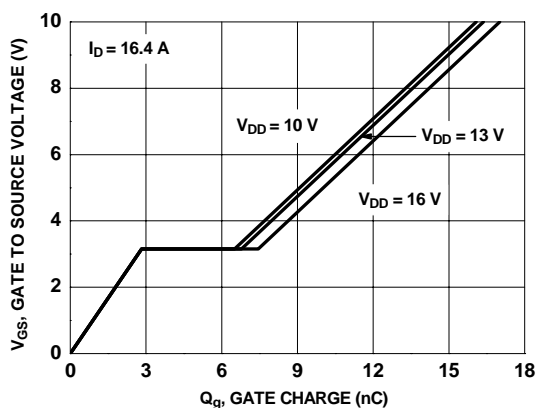


Figure 7. Gate Charge Characteristics

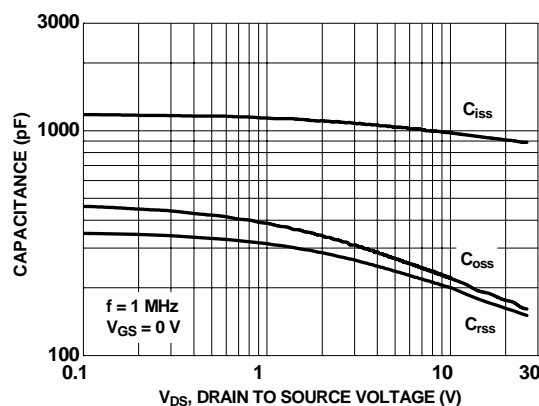


Figure 8. Capacitance vs Drain to Source Voltage

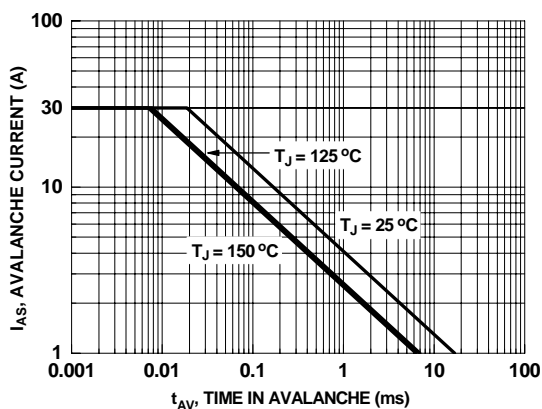


Figure 9. Unclamped Inductive Switching Capability

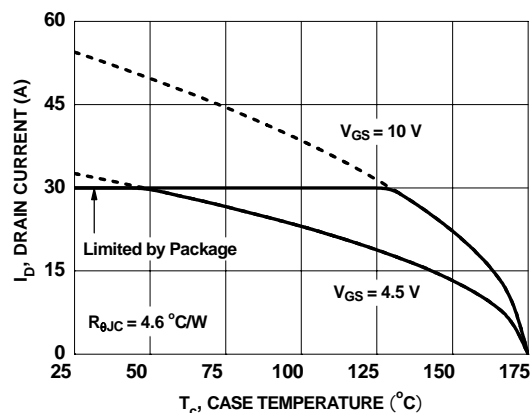


Figure 10. Maximum Continuous Drain Current vs Case Temperature

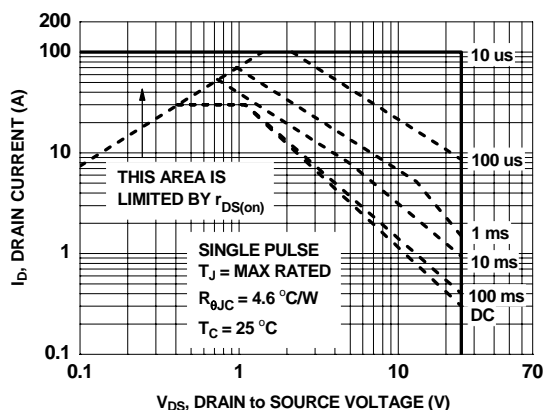


Figure 11. Forward Bias Safe Operating Area

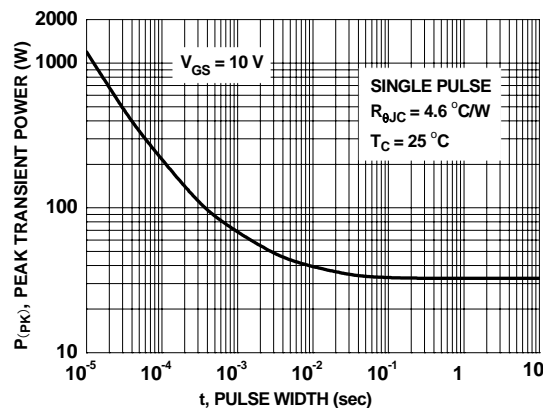


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted

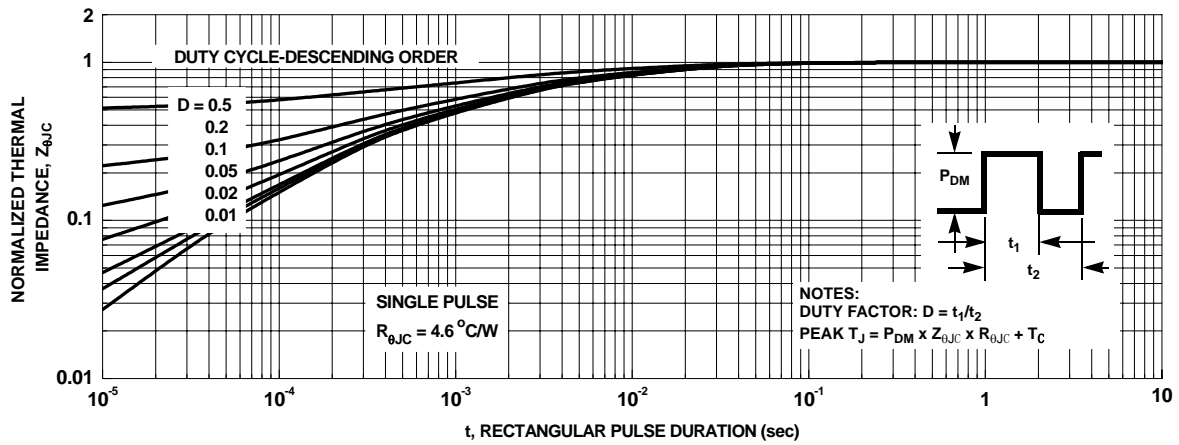


Figure 13. Transient Thermal Response Curve

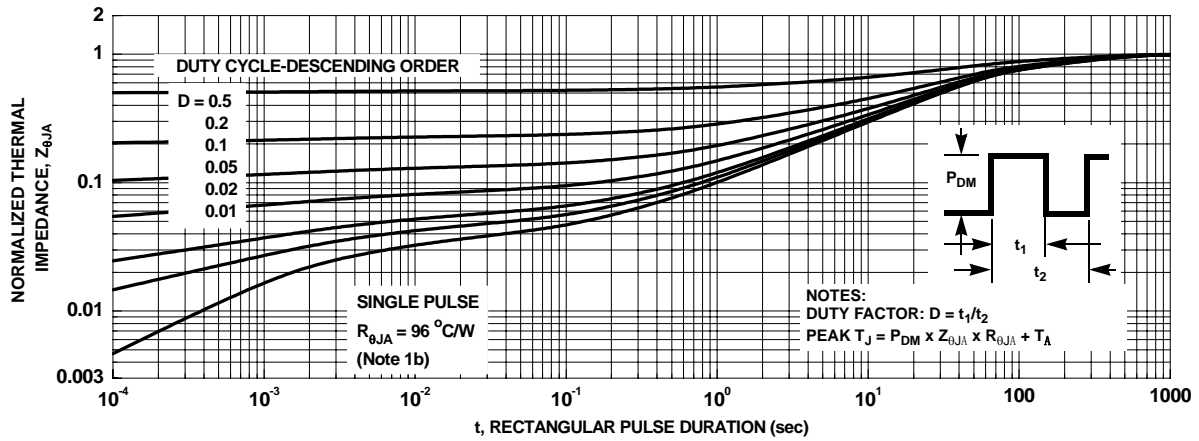


Figure 14. Transient Thermal Response Curve



## TRADEMARKS


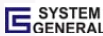
The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

Build it Now<sup>™</sup>  
CorePLUS<sup>™</sup>  
CorePOWER<sup>™</sup>  
CROSSVOL<sup>™</sup>  
CTL<sup>™</sup>  
Current Transfer Logic<sup>™</sup>  
EcoSPARK<sup>®</sup>  
EfficientMax<sup>™</sup>  
EZSWITCH<sup>™</sup> \*



Fairchild<sup>®</sup>  
Fairchild Semiconductor<sup>®</sup>  
FACT Quiet Series<sup>™</sup>  
FACT<sup>®</sup>  
FAST<sup>®</sup>  
FastvCore<sup>™</sup>  
FlashWriter<sup>®</sup> \*  
FPS<sup>™</sup>  
F-PFS<sup>™</sup>

FRFET<sup>®</sup>  
Global Power Resource<sup>SM</sup>  
Green FPS<sup>™</sup>  
Green FPS<sup>™</sup> e-Series<sup>™</sup>  
GTO<sup>™</sup>  
IntelliMAX<sup>™</sup>  
ISOPLANAR<sup>™</sup>  
MegaBuck<sup>™</sup>  
MICROCOUPLER<sup>™</sup>  
MicroFET<sup>™</sup>  
MicroPak<sup>™</sup>  
MillerDrive<sup>™</sup>  
MotionMax<sup>™</sup>  
Motion-SPM<sup>™</sup>  
OPTOLOGIC<sup>®</sup>  
OPTOPLANAR<sup>®</sup>  
  
PDP SPM<sup>™</sup>  
Power-SPM<sup>™</sup>  
PowerTrench<sup>®</sup>  
PowerXS<sup>™</sup>

Programmable Active Droop<sup>™</sup>  
QFET<sup>®</sup>  
QS<sup>™</sup>  
Quiet Series<sup>™</sup>  
RapidConfigure<sup>™</sup>  
  
Saving our world, 1mW /W /kW at a time<sup>™</sup>  
SmartMax<sup>™</sup>  
SMART START<sup>™</sup>  
SPM<sup>®</sup>  
STEALTH<sup>™</sup>  
SuperFET<sup>™</sup>  
SuperSOT<sup>™</sup>-3  
SuperSOT<sup>™</sup>-6  
SuperSOT<sup>™</sup>-8  
SupreMOST<sup>™</sup>  
SyncFET<sup>™</sup>  
  
The Power Franchise<sup>®</sup>

the power  
franchise<sup>™</sup>  
TinyBoost<sup>™</sup>  
TinyBuck<sup>™</sup>  
TinyLogic<sup>®</sup>  
TINYOPTO<sup>™</sup>  
TinyPower<sup>™</sup>  
TinyPWM<sup>™</sup>  
TinyWire<sup>™</sup>  
μSerDes<sup>™</sup>  
  
UHC<sup>®</sup>  
Ultra FRFET<sup>™</sup>  
UniFET<sup>™</sup>  
VCX<sup>™</sup>  
VisualMax<sup>™</sup>  
XS<sup>™</sup>

\* EZSWITCH<sup>™</sup> and FlashWriter<sup>®</sup> are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

## DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

## LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, [www.fairchildsemi.com](http://www.fairchildsemi.com), under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I37